



Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-22. (Canceled)

23. (Currently Amended) A method for manufacturing a semiconductor wafer ~~comprising~~comprising: steps of, at least:

obtaining a specification of a device maker's wafer order, and information of a device manufacturing ~~process;~~process from the device maker;

analyzing the information of the device manufacturing process and selecting a corresponding wafer manufacturing process which can manufacture a semiconductor wafer having wafer characteristics determined by the specification and the analysis of the information of the device manufacturing process; and

manufacturing a semiconductor wafer according to the selected wafer manufacturing process and said device manufacturing process information.

24. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information as for an apparatus used in the device manufacturing process.

25. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 24, wherein the information as for the apparatus used in the device manufacturing process includes information as for a wafer chuck of the apparatus.

26. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

27. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 25, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

28. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP (Chemical Mechanical Polishing) process, and an etching process.

29. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 27, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

30. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 23 further comprising a step of placing a laser mark on the semiconductor wafer indicating at least some of the information of the device manufacturing process.

31. (Previously Presented) The method for manufacturing a semiconductor wafer according to Claim 29 further comprising a step of placing a laser mark on the semiconductor wafer indicating at least some of the information of the device manufacturing process.

32. (Currently Amended) A method for receiving an order for manufacture of a semiconductor wafer ~~comprising, comprising: at least, a step of~~ connecting a device maker with a customer computer in a wafer maker through a ~~network; a step~~network, wherein the customer computer in the wafer maker receives from the device maker through a network at least a specification of a device maker's wafer order, and information of a device manufacturing process; ~~and, a step of~~and

analyzing the information of the device manufacturing process and selecting a wafer manufacturing process in which a semiconductor wafer having wafer characteristics determined by the specification and the analysis of the information of the device manufacturing process can be manufactured.

33. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information as for an apparatus used in the device manufacturing process in the device maker.

34. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 33, wherein the information as for the apparatus used in the device maker includes information as for a wafer chuck of the apparatus.

35. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

36. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 34, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

37. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

38. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 36, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

39. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32 further comprising a step of returning information of a semiconductor wafer to be manufactured in the selected wafer manufacturing process to the device maker.

40. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 38 further comprising a step of returning information of a semiconductor wafer to be manufactured in the selected wafer manufacturing process to the device maker.

41. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 39, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

42. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 40, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer.

43. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed

using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface..

44. (Previously Presented) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 42, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.

45. (Currently Amended) A system for receiving an order for manufacture of a semiconductor wafer, ~~comprising at least~~comprising:

a client terminal in a device ~~maker~~maker; and

a customer computer in a wafer maker,

wherein at least a specification of a device maker's wafer order, and information of a device manufacturing process in the device maker ~~is~~are inputted into the client terminal by the device maker, and the specification and the information of the device manufacturing process ~~is~~are sent through a network, the customer computer receives the sent specification and information of the device manufacturing process, the information of the device manufacturing process is analyzed, and a wafer manufacturing process which can manufacture the semiconductor wafer having wafer characteristics determined by the specification and the analysis of the information of the device manufacturing process is selected.

46. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device

manufacturing process includes information as for an apparatus used in the device manufacturing process.

47. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 46, wherein the information as for the apparatus used in the device manufacturing process includes information as for a wafer chuck of the apparatus.

48. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

49. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 47, wherein the information of the device manufacturing process includes information expressed with an ABC parameter, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

50. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

51. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 49, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

52. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the customer computer returns information of a semiconductor wafer as manufactured by the selected wafer manufacturing process to a client terminal.

53. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 51, wherein the customer computer returns information of a semiconductor wafer as manufactured by the selected wafer manufacturing process to a client terminal.

54. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 52, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

55. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 53, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer.

56. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer, said ABC parameter comprising a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

57. (Previously Presented) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 55, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.